

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

Claims 1-18. (canceled).

19. (new): A sealing member used for sealing of a semiconductor manufacturing equipment, said sealing member obtained by crosslinking a crosslinkable elastomer composition which comprises a crosslinkable elastomer component and a metal oxide filler containing a silicon oxide filler in an amount of not less than 60 % by weight of said metal oxide filler; said silicon oxide filler has a content of impurity metals other than silicon of not more than 100 ppm which is measured under the following conditions:

(i) the silicon oxide filler is dispersed and dissolved in 50 % hydrofluoric acid and is diluted with ultrapure water; and

(ii) contents of metals of the solution are determined through atomic absorption analysis by using an atomic absorption photometer.

20. (new): The sealing member of Claim 19, wherein said metal oxide filler consists of the silicon oxide filler.

21. (new): The sealing member of Claim 19, wherein said silicon oxide filler has quartz crystal structure.

22. (new): The sealing member of Claim 19, wherein said silicon oxide filler is blended in an amount of from 1 to 150 parts by weight on the basis of 100 parts by weight of the elastomer component.

23. (new): The sealing member of Claim 19, which contains a crosslinking agent and said silicon oxide filler in amounts of 0.05 to 10 parts by weight and 1 to 150 parts by weight, respectively on the basis of 100 parts by weight of the elastomer component.

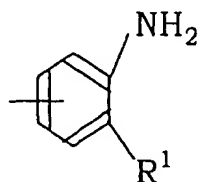
24. (new): The sealing member of Claim 19, wherein the elastomer component is a fluorine-containing elastomer.

25. (new): The sealing member of Claim 24, wherein the elastomer component is a fluorine-containing elastomer capable of being crosslinked with a peroxide crosslinking agent.

26. (new): The sealing member of Claim 24, wherein the elastomer component is a fluorine-containing elastomer capable of being crosslinked with an imidazole, oxazole, thiazole or triazine crosslinking agent.

27. (new): The sealing member of Claim 24, wherein the crosslinking agent is an organic peroxide.

28. (new): The sealing member of Claim 24, wherein the crosslinking agent is a compound having at least two functional groups represented by the formula (I):



wherein R<sup>1</sup> is any one of OH, NH<sub>2</sub> or SH.

29. (new): The sealing member of Claim 19, wherein an increasing rate of particles generated by irradiating oxygen plasma to the article is not more than 1,000 %.

30. (new): The sealing member of Claim 29, wherein the sealing member is used for sealing of a semiconductor manufacturing equipment for dry process.

31. (new): The sealing member of Claim 19, wherein an amount of impurity metals other than silicon which are extracted with a 50 % aqueous solution of HF is not more than 200 ppb.

32. (new): The sealing member of Claim 19, which contains impurity metals other than silicon in an amount of not more than 100 ppm.

33. (new): The sealing member of Claim 31, wherein the sealing member is used for sealing of a semiconductor manufacturing equipment for wet process.

34. (new): The sealing member of Claim 33, wherein the sealing member is used for sealing of a semiconductor manufacturing equipment for a process with ultrapure water.